# **LNJ837W83RA**

### Hight Bright Surface Mounting Chip LED

#### ESS II Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	55	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

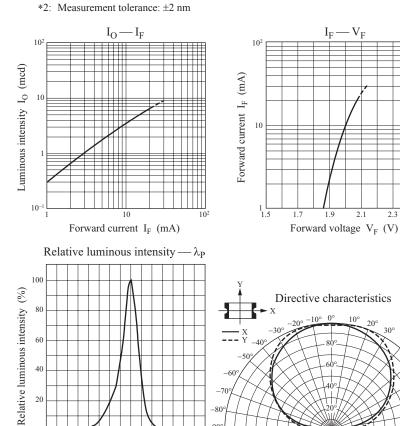
• Orange

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 5 \text{ mA}$	11.5	17.5	47.3	mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{P}$	$I_F = 5 \text{ mA}$		630		nm
Dominant emission wavelength *2	λ <sub>d</sub>	$I_F = 5 \text{ mA}$	615	620	627	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		13		nm

Note) \*1: Measurement tolerance: ±20%



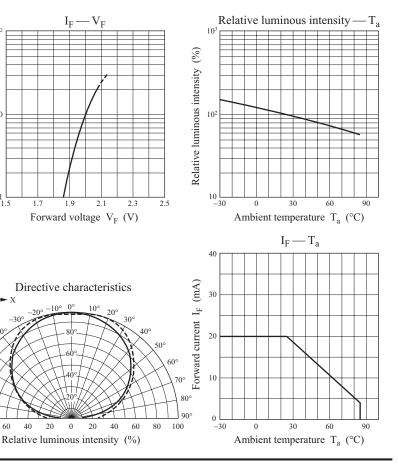
-90°

700 100

80

60

40 20



600

Peak emission wavelength  $\lambda_P~(nm)$ 

650

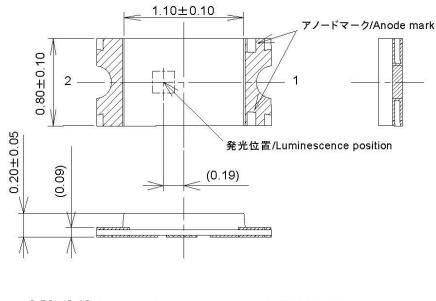
0 550

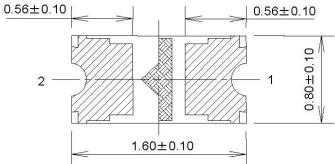
0

20 40 2.3

#### Package (Unit: mm)

## KLTFTN2K3700





• Pin name

1: Anode

2: Cathode

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